

7. (Amended) A semiconductor apparatus, comprising:
- a semiconductor device having a plurality of electrodes;
- a substrate main body;
- a plurality of leads formed on the substrate main body, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body;
- and
- a plurality of conduction sections formed on the substrate main body, [wherein] the conduction sections [are] being electrically connected to the leads, and one of the conduction sections [defines] defining an external terminal.

19. (Amended) A method of manufacturing semiconductor apparatus, comprising:
- preparing a substrate having a mounting surface for mounting the semiconductor device;
- forming a plurality of leads on the mounting surface, the plurality of leads radially extending from a peripheral area toward a central area of the substrate main body;
- and
- forming a plurality of conduction sections each defining at least part of an external terminal, and electrically connecting the conduction sections to the leads.

REMARKS

Claims 1-4, 6-12 and 19-25 are pending. By this Amendment, claim 5 is canceled and claims 1, 7 and 19 are amended to recite the features of claim 5, and for further clarity. No new matter is added.

The Office Action asserts that claims 1-12 and 19-25 are subject to U.S. restriction requirement. This assertion is respectfully traversed.